

The background of the top half of the slide is a grayscale image of a printed circuit board (PCB) with intricate white traces and circular pads. The text 'Ucamco' is overlaid in a bold, red, sans-serif font. A horizontal red line extends from the bottom of the 'U' across the width of the text, ending in a red sunburst icon on the right side.

Ucamco

YELO – 阻焊优化 (MAJ)

网络研讨会 August 05, 2020

✦ 网络研讨会如何进行？

- 所有与会者均采静音
- 透过“问号”图标提问
- 问与答时间 提供回复
- 研讨会结束后 演示视频发布

✦ 工作人员

- 主持人: Lico
- 主講人: Saxo

✦ 主要内容

- Ucamco 公司简介
- YELO 阻焊优化 功能介绍 (MAJ)
- 软件演示直播
- 问与答

Ucamco 为全球 PCB 行业服务

激光绘图机

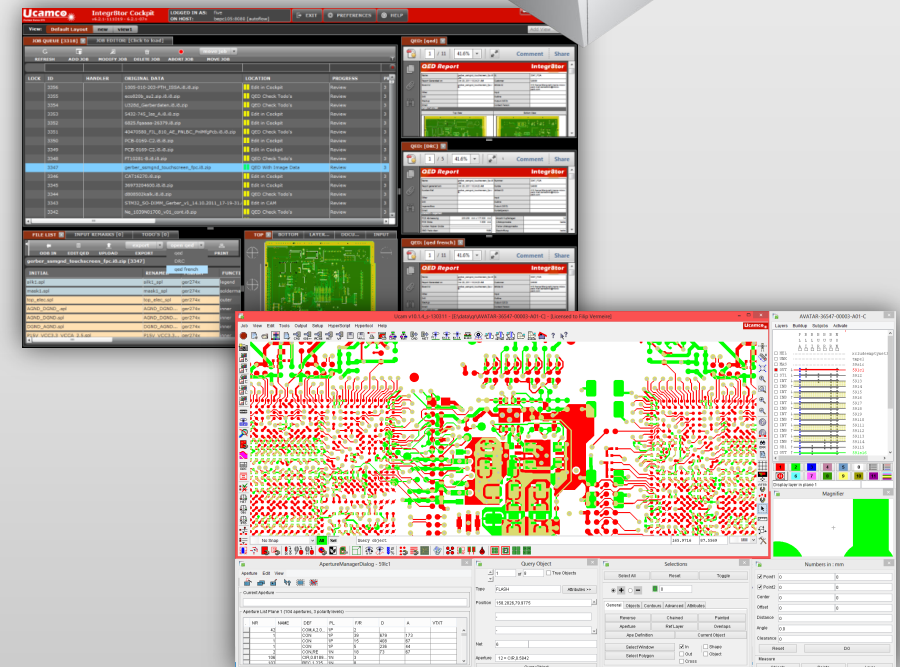
- 一流的性能
- 绝佳稳定度
- 超细线能力

PCB 制造 工程软件

- Integr8tor, UcamX
- Web-based: iamcam, Communic8tor

PCB 设备前端处理软件

Gerber 格式开发: X2, X3, Gerber Job



YELO Mask Adjuster

Parameter Set
YELO-MAJ

Data Preparation
Drill Tool Manager Markup Assistant

Adjust Mask
Ring 0.075 Ignore rings bigger than set value
Copper overhang 0.05
Solder web 0.1 Mask to Mask 0.075
Adjust

Via Handling
 Ignore mask rings larger than set value

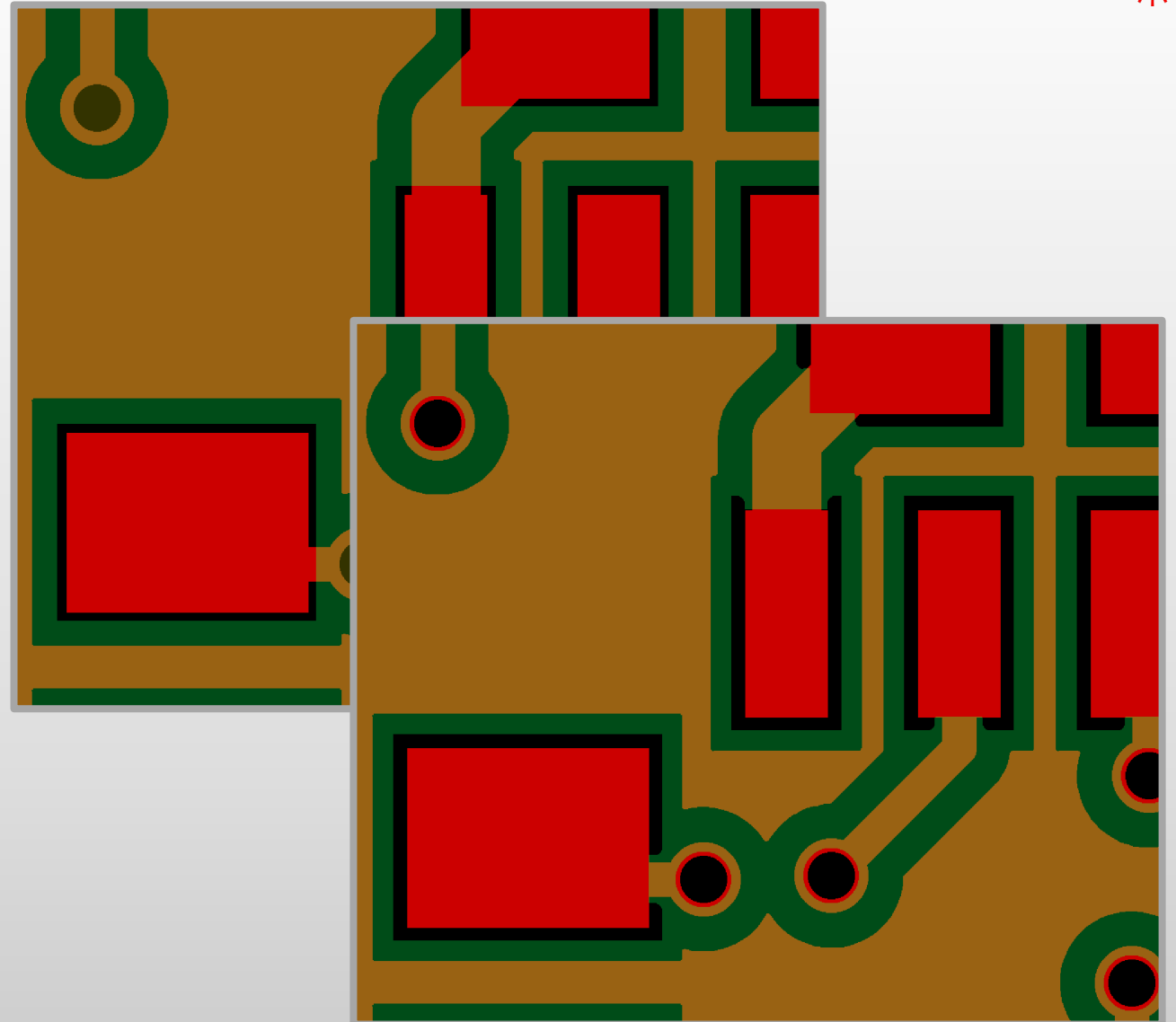
	Reference	Ring +/-
<input checked="" type="checkbox"/> Via with dedicated copper pad free or partially free of mask	<input type="radio"/> Pad <input checked="" type="radio"/> Hole	0.03
<input checked="" type="checkbox"/> Via with dedicated copper covered by mask	<input type="radio"/> Pad <input checked="" type="radio"/> Hole	0.05
<input checked="" type="checkbox"/> Via without dedicated copper pad free or partially free of mask	<input checked="" type="radio"/> Hole	0.075
<input checked="" type="checkbox"/> Via without dedicated copper covered by mask	<input checked="" type="radio"/> Hole	0.1

Apply

Adjust Mask for Embedded Pads
Soldermask ring for in copper pads 0
Soldermask ring reduction if no pad in copper 0
Soldermask ring overlap on tracks 0.025
Clearance soldermask to tracks (transition) 0.05
Adjust

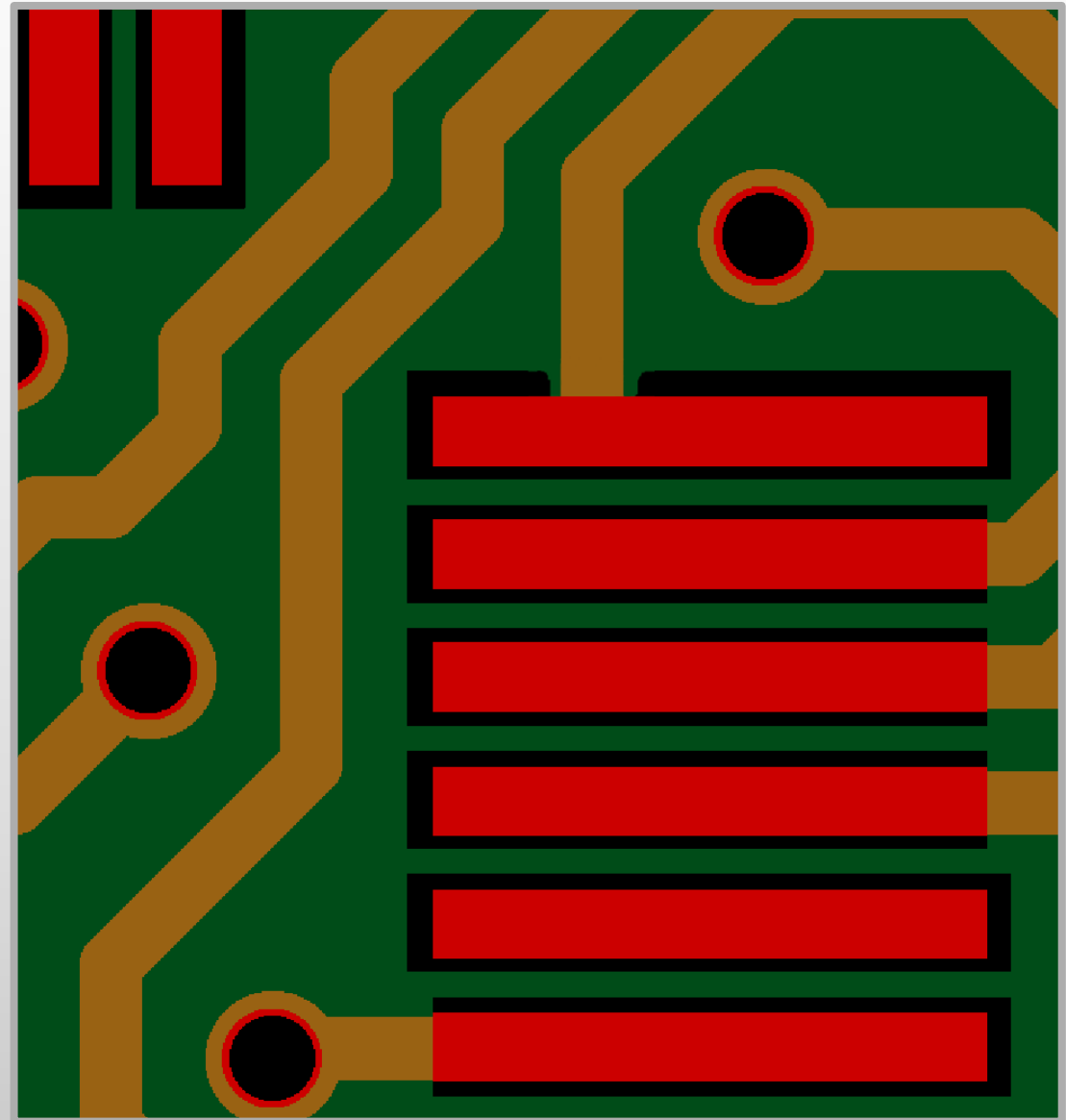
Remodel soldermask (eliminate negatives)
 Backup Original Layers

Apply and Adjust Cancel



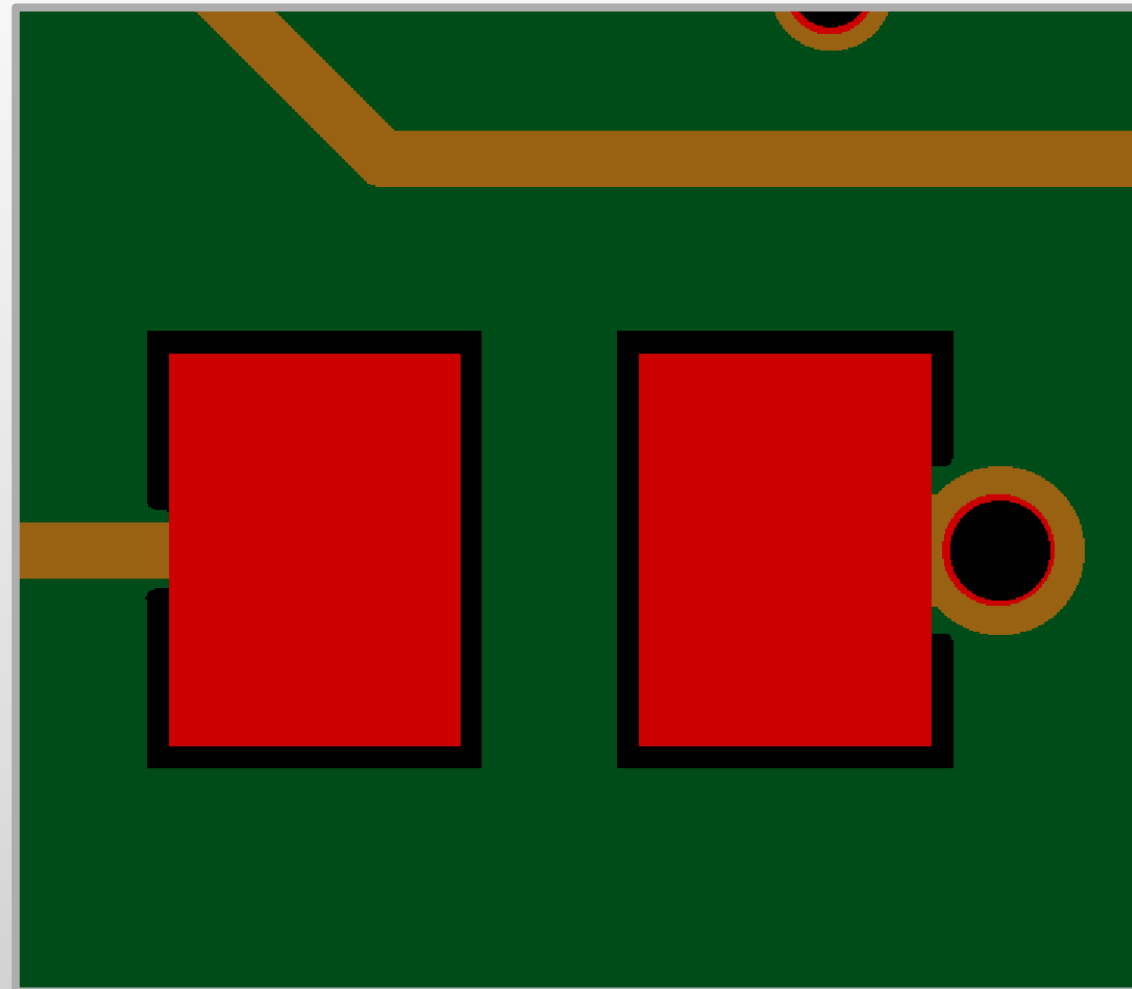
为什么要调整阻焊？

- 增加对位能力
- 避免绿油上焊盘
- 提升阻焊工艺良率
- 避免焊盘与外部铜短路
- 防止焊料不足 焊接缺陷
- 减少贴装制程的人工干预
- 满足终端客户要求



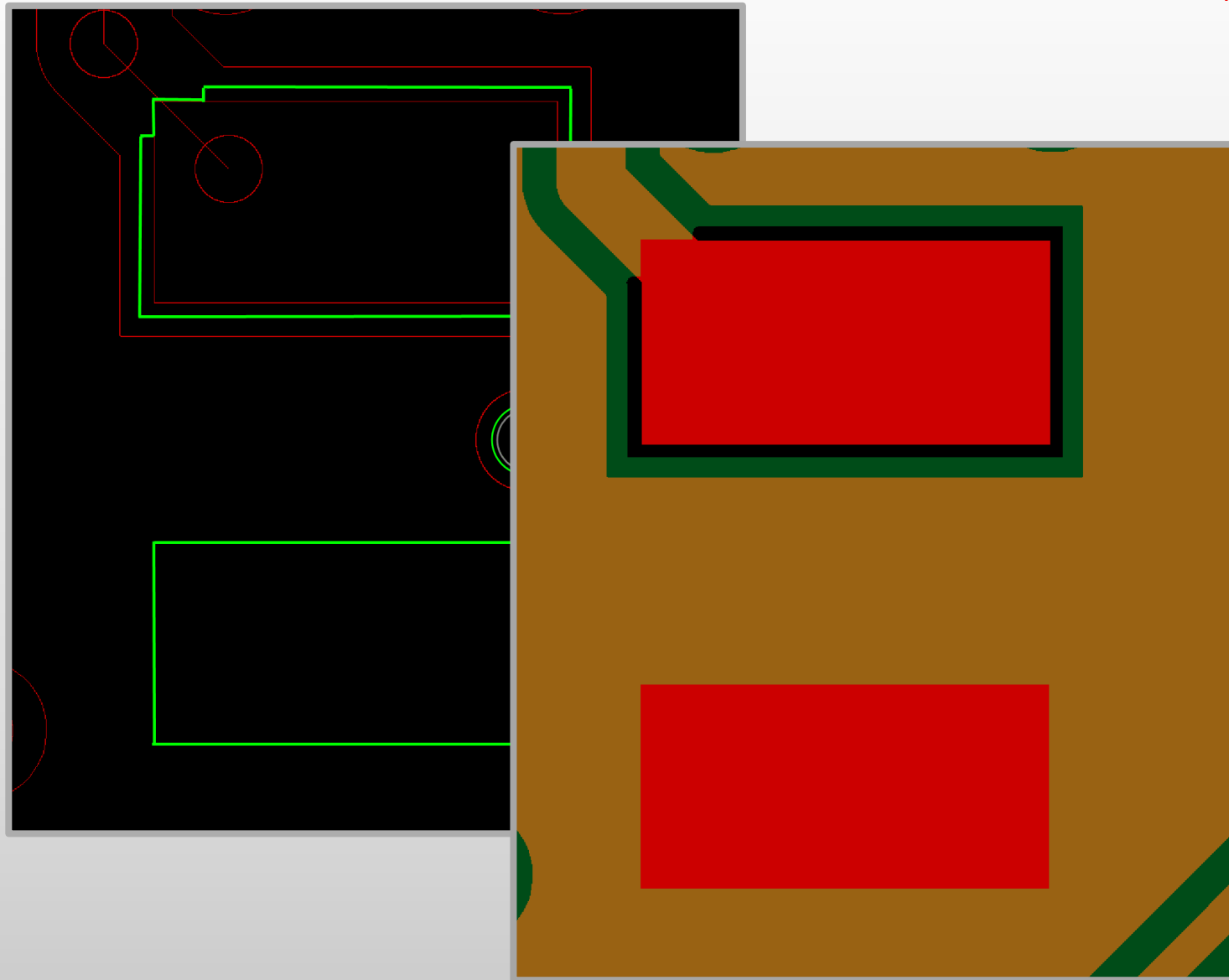
特点

- 一般优化:
 - 阻焊环 soldermask ring
 - 负净空度 overhang
 - 开窗间距 mask to mask
 - 隔焊 solder web (dam)
- 过孔优化:
针对过孔阻焊设计
创建过孔开窗



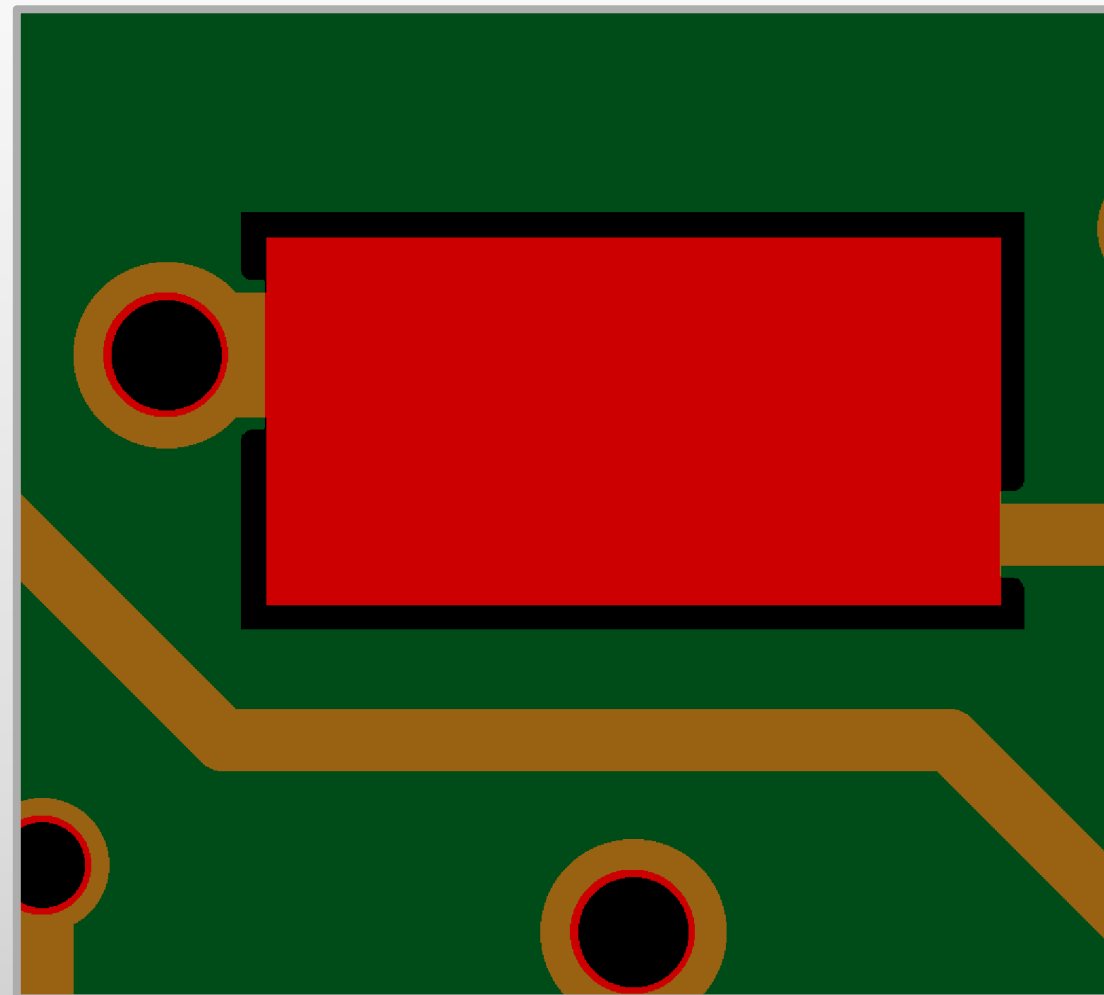
特点

- 大铜皮 开窗优化
- 脖子位 开窗优化

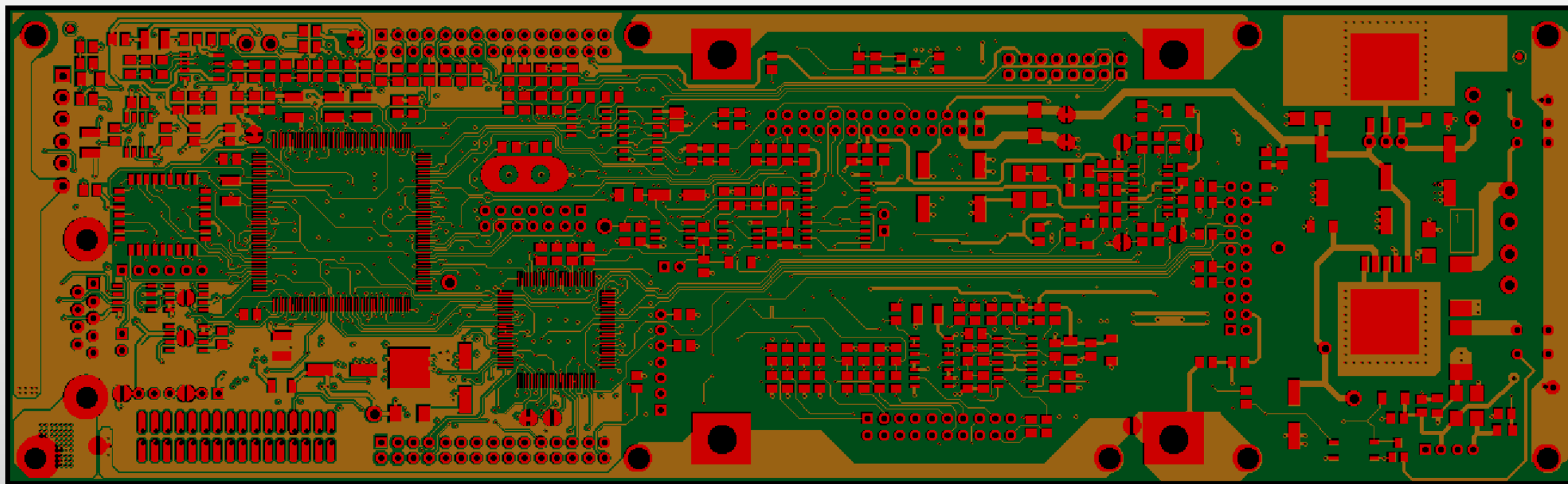


✱ 特点

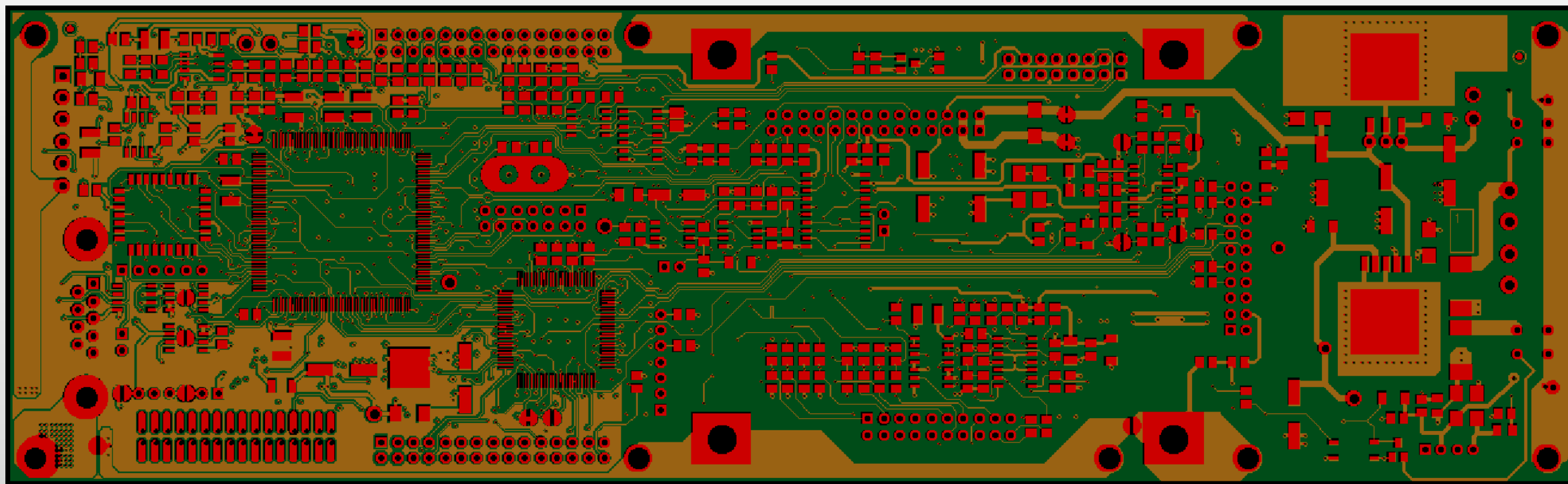
- 舒适与便利的用户介面
- 可保存和重复使用的配置参数
- 为每个优化步骤添加备份层以进行快速比对



- 软件演示直播



- Lico 问与答 答复



好处

- 提升阻焊工艺能力
- 无与伦比的优化范围
- 一键到位 全自动运算处理
- 防止焊料不足
- 阻止短路发生
- 改善贴装工艺的 立碑 空焊问题
- 达成客户要求

有兴趣吗? 可通过 webinars@ucamco.com 與我們联系

未回答的问题 网络研讨会后，将通过电子邮件答复

我们期待您的反馈

将通知您 新的网络研讨会

感谢您今天的参与。

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